

Abstract

A leadframe which is to be fitted with a semiconductor chip (2) and is to be encapsulated with a plastic compound (4) has a metallic single-piece base body (3), to which an interlayer (5) is applied. The interlayer (5) has a surface (6) comprising a matrix of islands (14) of remaining material of substantially uniform height, with voids (10) extending between said islands.

[Figure 1]